S1AF THRU S1MF

Features

- For surface mounted applications
- Low profile package
- Glass Passivated Chip Junction
- Easy to pick and place
- Lead free in comply with EU RoHS 2011/65/EU directives

Simplified outline SMAF and symbol

Mechanical Data

- Case: SMAF
- Terminals: Solderable per MIL-STD-750, Method 2026
- APPROX. Weight: 27mg / 0.00095oz

Pinning

PIN	DESCRIPTION
1	Cathode
2	Anode

Absolute Maximum Ratings And Characteristics

Ratings at 25℃ ambient temperature unless otherwise specified.

Single phase, half wave, 60 Hz, resistive or inductive load. For capacitive load, derate current by 20%.

Parameter	Symbols	S1AF	S1BF	S1DF	S1GF	S1JF	S1KF	S1MF	Units
Maximum Repetitive Peak Reverse Voltage	V_{RRM}	50	100	200	400	600	800	1000	V
Maximum RMS voltage	V_{RMS}	35	70	140	280	420	560	700	V
Maximum DC Blocking Voltage	V_{DC}	50	100	200	400	600	800	1000	V
Maximum Average Forward Rectified Current at Tc = 125 °C	$I_{F(AV)}$	1							A
Peak Forward Surge Current 8.3 ms Single Half Sine Wave Superimposed on Rated Load	I_{FSM}	30							A
Maximum Forward Voltage at 1 A	V_F	1.1							V
Maximum DC Reverse Current Ta = 25 °C at Rated DC Blocking Voltage Ta =125 °C	I_R	5 50							μA
Typical Junction Capacitance (1)	C_j	15							pF
Typical Thermal Resistance (2)	RθJA RθJC	80 27							℃/W
Operating and Storage Temperature Range	T_j, T_{stg}	-55 ~ +150							℃

（1）Measured at 1 MHz and applied reverse voltage of 4 V D.C

（2）P.C.B. mounted with 2.0" X 2.0" (5 X 5 cm) copper pad areas.

Rating And Characteristic Curves

Fig.1 Forward Current Derating Curve

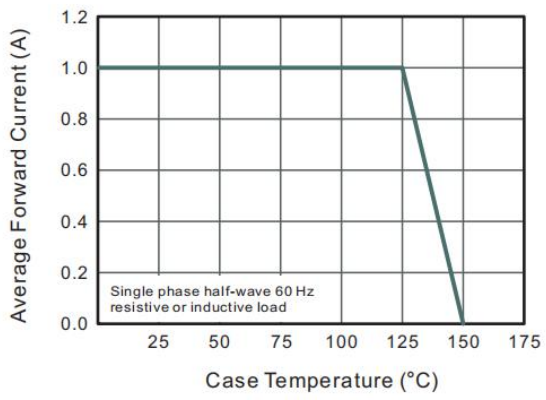


Fig.2 Typical Instaneous Reverse Characteristics

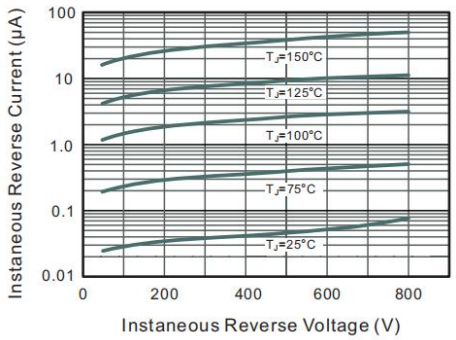


Fig.3 Typical Forward Characteristic

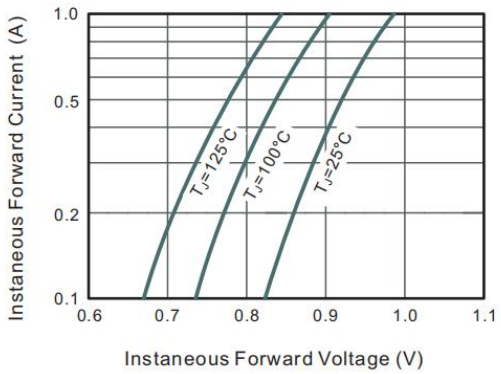


Fig.4 Typical Junction Capacitance

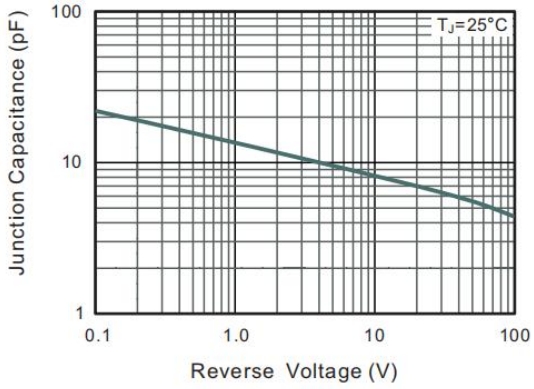
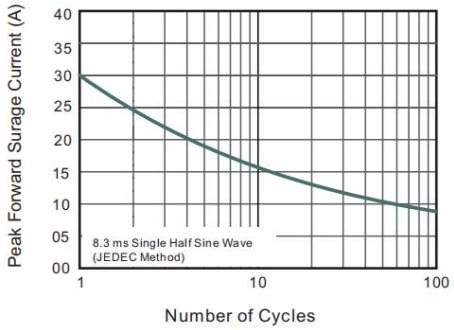


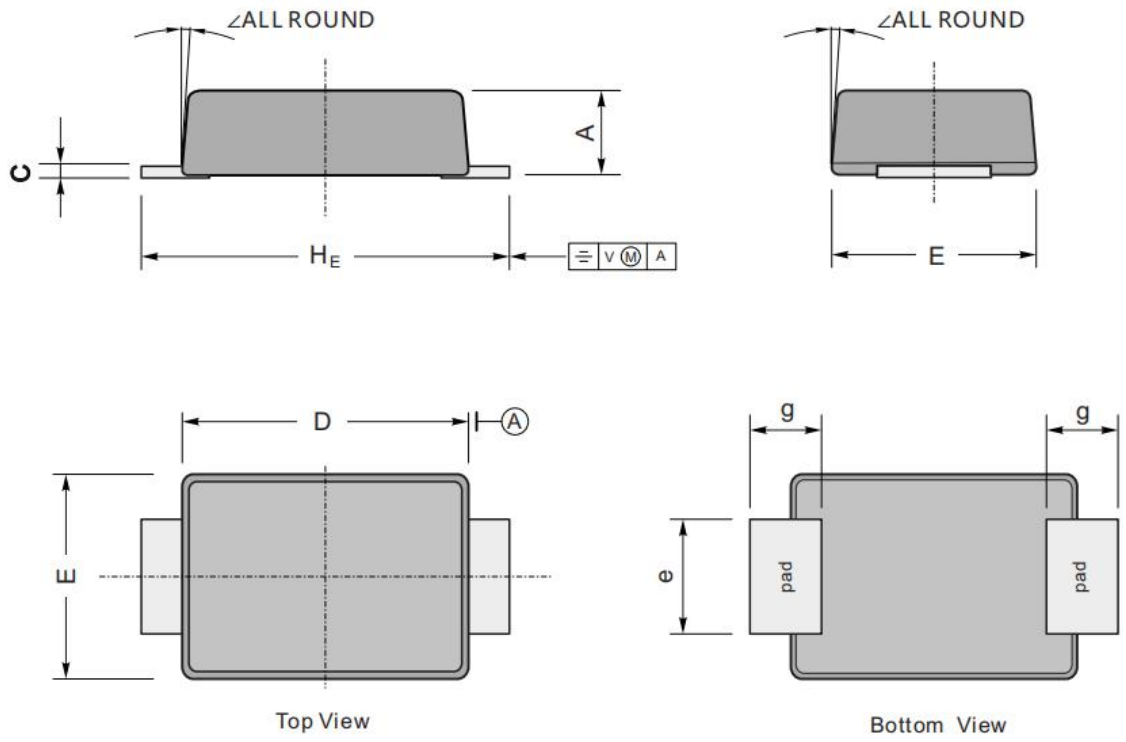
Fig.5 Maximum Non-Repetitive Peak

Forward Surge Current



Package Outline

Plastic surface mounted package; 2 leads SMAF



UNIT		A	C	D	E	e	g	HE	∠
mm	max	1.2	0.20	3.7	2.7	1.6	1.2	4.9	7°
	min	0.9	0.12	3.3	2.4	1.3	0.8	4.4	
mil	max	47	7.9	146	106	63	47	193	
	min	35	4.7	130	94	51	31	173	

The recommended mounting pad size